



PRODUCT DATASHEET



- PTH Housing Lamp
- 1x 3.0mm Round
- Red (625nm)

NOR09H22SV

3.0mm Hosing Lamp

APPLICATIONS:

Side View Application

Indicator

Signal

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3.0mm Housing Lamp Compliant

FEATURES:

- Package: PTH Housing Lamp 1x 3.0mm Round
- Forward Current: 20mA
- Forward Voltage (typ.): 2.1V
- Luminous Intensity (typ.): 38mcd@20mA
- Colour: Red
- Wavelength: 625nm
- Viewing angle: 76°
- Materials:
 - Die: GaAsP on GaP
 - Resin: Epoxy (Red Diffused)
 - Holder: Nylon 66 Black
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- Grouping parameters:
 - Forward voltage
 - Luminous intensity
 - Wavelength
- Soldering methods: Hand; Reflow soldering
- Preconditioning: acc. to JEDEC Level 3
- Packing: 500pcs/Bulk

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CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	25	mA
Peak Forward Current Duty 1/10@10KHz	I _{FP}	100	mA
Reverse Voltage	V _R	5	V
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	PD	85	mW
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

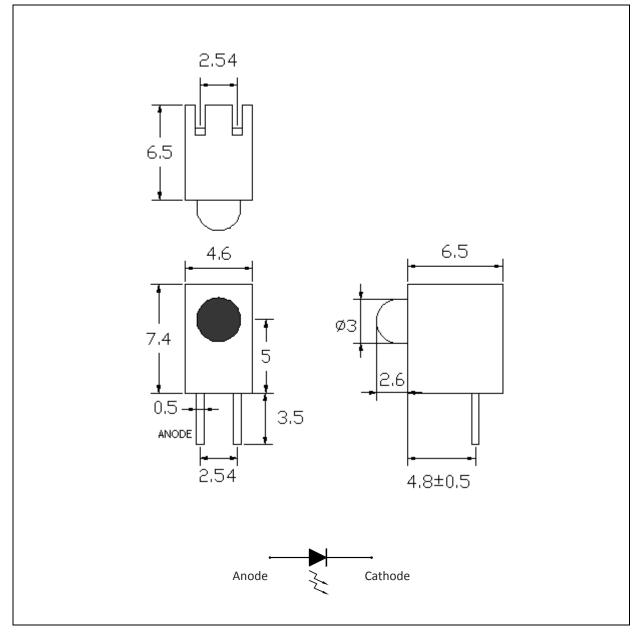
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Sumbol	Values			Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	$V_{\rm F}$	1.9	2.1	2.6	V	I _F =20mA
Luminous Intensity	Ι _ν	25	38	55	mcd	I _F =20mA
Dominant Wavelength	λ_{D}	620	625	630	nm	I _F =20mA
Peak Wavelength	λ_{P}		635		nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ		45		nm	I _F =20mA
Viewing Angle	20 _{1/2}		50		deg	I _F =20mA



OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).

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2. Tolerance ±0.1mm, unless otherwise noted.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
V1	1.9	2.6	V

Luminous Intensity Classifications (I_F = 20mA):

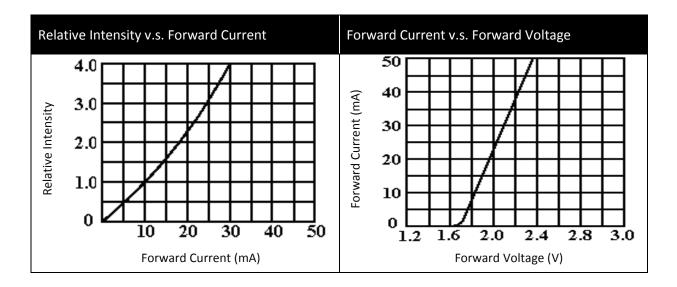
Code	Min.	Max.	Unit
X1	25	55	mcd

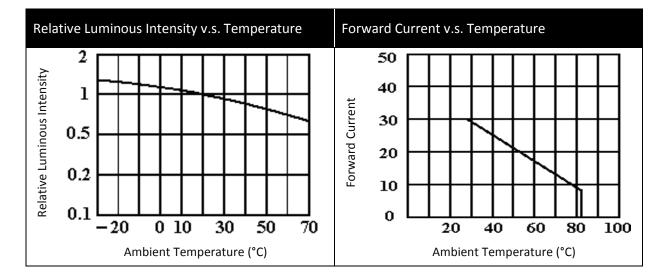
Wavelength Classifications ($I_F = 20mA$):

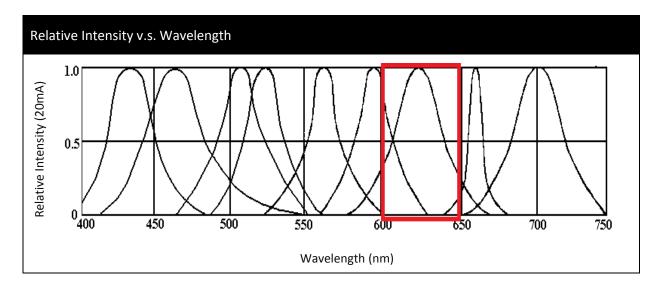
Code	Min.	Max.	Unit
R1	620	630	nm



ELECTRO-OPTICAL CHARACTERISTICS:







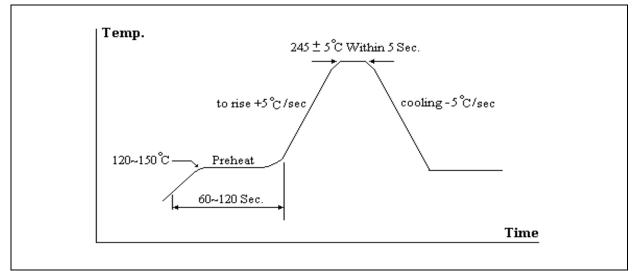


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 300°C Max. (25W Max.).
- Soldering Time: 3 seconds ± 1 sec.
- Maximum reflow soldering: 1 time.

Reflow Solder:

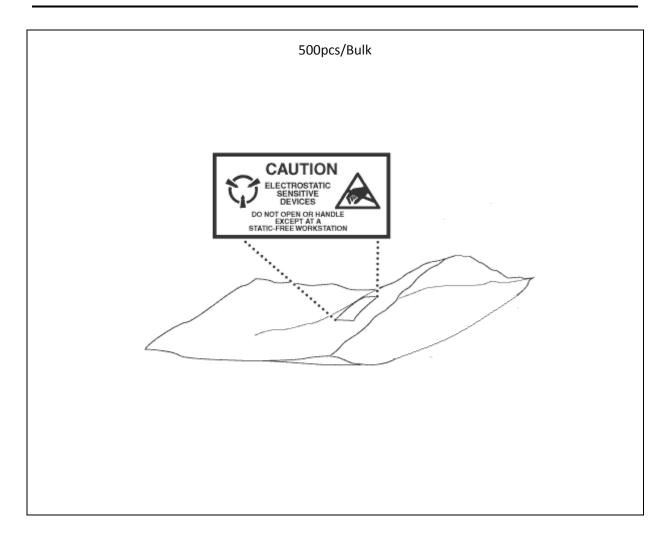


Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:



PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

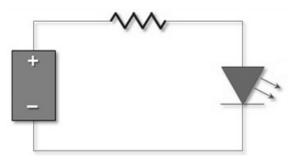
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

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REVISION RECORD:

Version	Date	Summary of Revision
A1.0	27/08/2015	Datasheet set-up.

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